- **Advanced, Integrated Speech Synthesizer for High-Quality Sound.**
- **Operates up to 12.32 MHz (Performs up to 12 MIPS)**
- **Very Low-Power Operation, Ideal For Hand-Held Devices.**
- **Low-Voltage Operation, Sustainable by Three Batteries**
- **Reduced Power Stand-By Modes, Less Than 10 μA in Deep-Sleep Mode**
- **Supports High-Quality Synthesis Algorithms Such as MELP, CELP, LPC and ADPCM**
- **Contains 32K Words Onboard ROM (2K Words Reserved)**
- **640-Word RAM**
- **1.83 Mb of Onboard ROM for Up to 35 Minutes of Speech Data**
- **24 General-Purpose, Bit Configurable I/O**
- **8 Inputs With Programmable Pullup Resistors and a Dedicated Interrupt (Key-Scan)**
- **Direct Speaker Driver, 32 Ω (PDM)**
- **One-bit Comparator With Edge-Detection Interrupt Service**
- **Resistor-Trimmed Oscillator or 32.768 kHz Crystal Reference Oscillator**
- **Serial Scan Port for In-Circuit Emulation and Diagnostics**
- **The MSP50C605 Is Sold in Die Form or 100-Pin PJM Package.**
- **An Emulator Device Is Available in a Ceramic Package for Development**

description

The MSP50C605 (C605) is a low-cost, mixed-signal processor that combines a speech synthesizer, general-purpose I/O, onboard ROM, and direct speaker drive in a single package. The computational unit utilizes a powerful new DSP which gives the C605 unprecedented speed and computational flexibility compared with previous devices of its type. The C605 supports a variety of speech and audio coding algorithms, providing a range of options with respect to speech duration and sound quality.

The device consists of a micro-DSP core, embedded program, and data memory, and a self-contained clock generation system. General-purpose periphery is comprised of 32 bits of partially configurable I/O.

The core processor is a general-purpose 16-bit microcontroller with DSP capability. The basic core block includes computational unit (CU), data address unit, program address unit, two timers, eight level interrupt processor, and several system and control registers. The core processor gives the C605 break-point capability in emulation.

The processor is Harvard type for efficient DSP algorithm execution. It requires separate program and data memory blocks to permit simultaneous access. The ROM has a protection scheme to prevent third-party pirating. It is configured in 32K 17-bit words.

The total ROM space is divided into three areas: 1) The lower 2K words are reserved by Texas Instruments for the purposes of a built-in self-test 2) The upper 30K is for user program/data 3) A 1.83 Mb ROM provides data for up to 30 minutes of speech.

The data memory is internal static RAM. The RAM is configured in 640 17-bit words. All memories are designed to consume minimum power at a given system clock and algorithm acquisition frequency.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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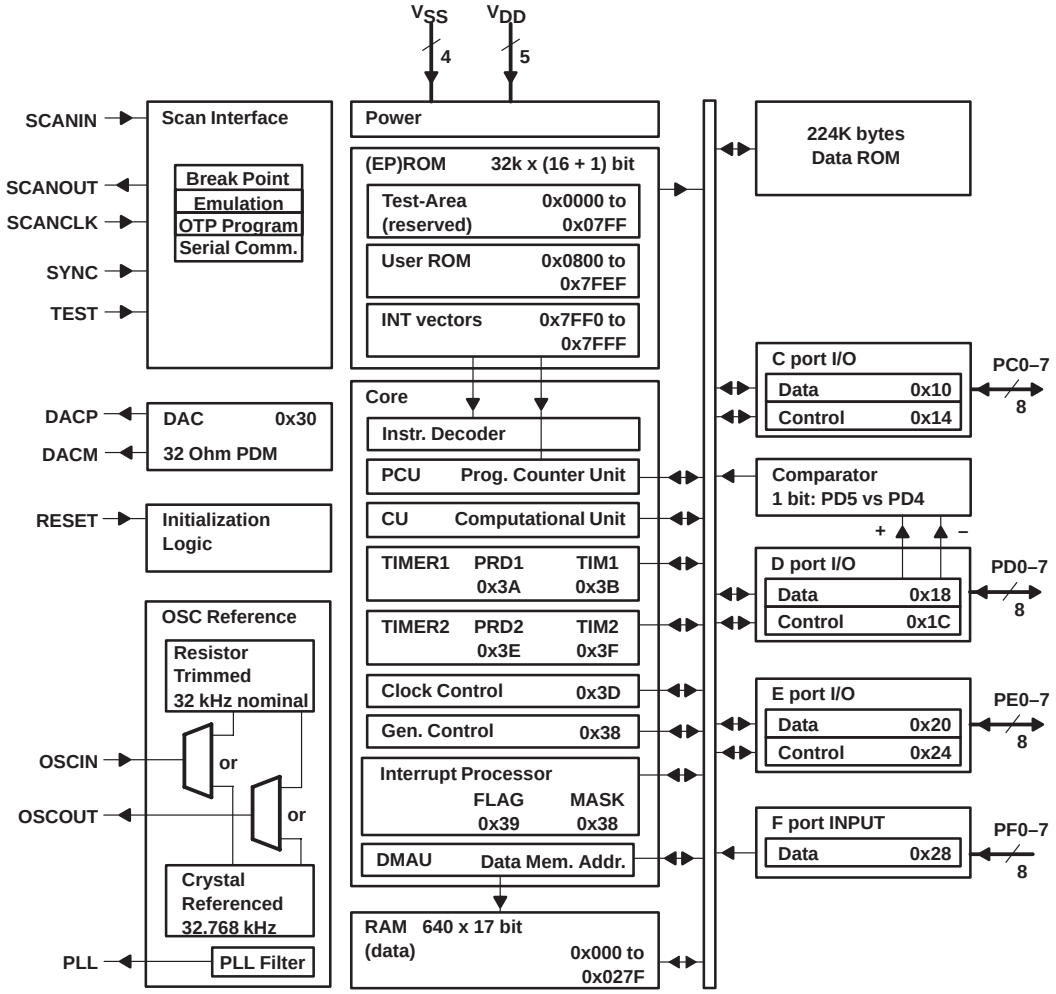
description (continued)

A flexible clock generation system enables the software to control the clock over a wide frequency range. The implementation uses a phase-locked loop (PLL) circuit that drives the processor clock at a selectable frequency between the minimum and maximum achievable. Selectable frequencies for the processor clock are spaced apart in 65.536 kHz steps. The PLL clock-reference is also selectable; either a resistor-trimmed oscillator or a crystal-referenced oscillator may be used. Internal and external clock sources are controlled separately to provide different levels of power management.

The periphery consists of three 8-bit wide general-purpose I/O ports and one 8-bit wide dedicated input port. The bidirectional I/O can be configured under software control as either high-impedance inputs or as totem-pole outputs. They are controlled via addressable I/O registers. The input-only port has a programmable pullup option (70-kΩ minimum resistance) and a dedicated service interrupt. These features make the input port especially useful as a key-scan interface.

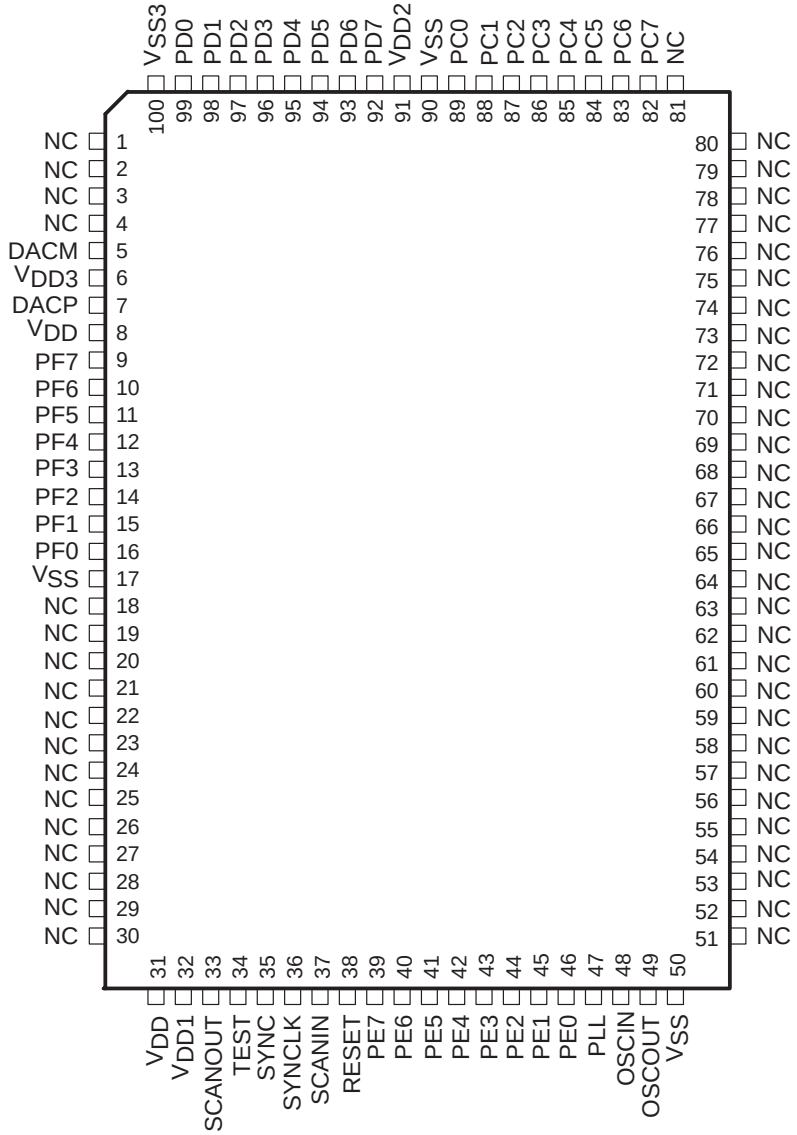
A simple one-bit comparator is also included in the periphery. The comparator is enabled by a control register, and its pin access is shared with two pins in one of the general-purpose I/O ports. Rounding out the C605 periphery is a built-in pulse-density-modulated DAC (digital-to-analog converter) with direct speaker-drive capability. The functional block diagram gives an overview of the C605 functionality.

functional block diagram



pin assignments

PJM PACKAGE
(TOP VIEW)



pin assignments

Table 1. Signal and Pad Descriptions for the C605

SIGNAL	PIN NUMBER	PAD NUMBER	I/O	DESCRIPTION	
Input/Output Ports					
PC0 – PC7	89 – 82	8 – 1	I/O	Port C general-purpose I/O	(1 Byte)
PD0 – PD7	99 – 92	18 – 11	I/O	Port D general-purpose I/O	(1 Byte)
PE0 – PE7	46 – 39	48 – 41	I/O	Port E general-purpose I/O	(1 Byte)
PF0 – PF7	16 – 9	31 – 24	I	Port F key-scan input	(1 Byte)
Pins PD_4 and PD_5 may be dedicated to the comparator function, if the comparator enable bit is set. Refer to Section 3.3, *Comparator*, for details.					
Scan Port Control Signals					
SCANIN	37	39	I	Scan port data input	
SCANOUT	33	35	O	Scan port data output	
SCANCLK	36	38	I	Scan port clock	
SYNC	35	37	I	Scan port synchronization	
TEST	34	36	I	C605: test modes	
The scan port pins must be bonded out on any C605 production board. Consult the “Important Note regarding Scan Port Bond Out”, see Chapter 7 in the MSP50C614 User’s Guide (SPSU014).					
Oscillator Reference Signals					
OSCOUT	49	51	O	Resistor/crystal reference out	
OSCIN	48	50	I	Resistor/crystal reference in	
PLL	47	49	O	Phase-lock-loop filter	
DAC Sound Output					
DACP	7	22	O	Digital-to-analog output 1 (+)	
DACM	5	20	O	Digital-to-analog output 2 (–)	
Initialization					
RESET	38	40	I	Initialization	
Power Signals					
V_{SS}	17, 50, 90, 100†	32, 52, 9, 19†		Ground	
V_{DD}	6†, 8, 31, 32, 91	21†, 23, 33, 34, 10		Processor power (+)	

† The V_{SS} and V_{DD} connections service the DAC circuitry. Their pins tend to sustain a higher current draw. A dedicated decoupling capacitor across these pins is therefore required.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} (see Note 1) . . . . . –0.3 to 7 V
Supply current, I_{DD} (see Note 2) . . . . . 35 mA
Input voltage range, V_I (see Note 1) . . . . . –0.3 to V_{DD} + 0.3 V
Output voltage range, V_O (see Note 1) . . . . . –0.3 to V_{DD} + 0.3 V
Storage temperature range, T_A . . . . . –30°C to 125°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Unless otherwise noted, all voltages are measured with respect to V_{SS} .
2. The total supply current includes the current out of all the I/O pins as well as the operating current of the device.

recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
V_{DD}	Supply voltage (with respect to V_{SS})			3	5.2	V
V_{IH}	High-level input voltage	V_{DD} = 3 V		2	3	V
		V_{DD} = 4.5 V		3	4.5	
		V_{DD} = 5.2 V		3.5	5.2	
V_{IL}	Low-level input voltage	V_{DD} = 3 V		0	1	V
		V_{DD} = 4.5 V		0	1.5	
		V_{DD} = 5.2 V		0	1.7	
I_{OH}‡	High-level output current per pin of I/O port	V_{DD} = 4.5 V,	V_{OH} = 4 V		–2	mA
I_{OL}‡	Low-level output current per pin of I/O port	V_{DD} = 4.5 V,	V_{OL} = 0.5 V		5	mA
$I_{OH\ (DAC)}$	High-level output DAC current	V_{DD} = 4.5 V,	V_{OH} = 4 V		–10	mA
$I_{OL\ (DAC)}$	Low-level output DAC current	V_{DD} = 4.5 V,	V_{OL} = 0.5 V		20	mA
$f_{(CPU)}$	CPU clock rate (as programmed)			64	12,320	kHz
$R_{(DAC)}$	Resistance between DAC_P and DAC_M			32		Ω
T_A	Operating free-air temperature	Device functionality		0	70	°C

‡ Cannot exceed 15 mA total per internal V_{DD} pin. Port A, B share 1 internal V_{DD} pin; Port C, D share 1 internal V_{DD}.

timing requirements

	TEST CONDITIONS	MIN	MAX	UNIT
$t_{(RESET)}$	Reset low pulse width, while V_{DD} is within specified limits	100		ns
$t1_{(WIDTH)}$	Pulse width required prior to a negative transition at pin...PD3, PD5, or PF0...PF7†	2		$1/F_{CPU}$
$t2_{(WIDTH)}$	Pulse width required prior to a positive transition at pin...PD2 or PD4†	2		$1/F_{CPU}$

† While these pins are being used as interrupt inputs.

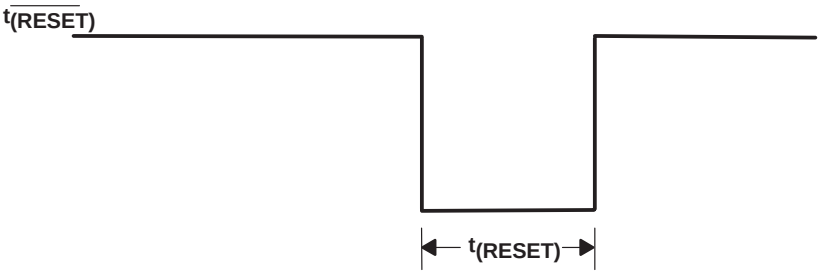


Figure 1. Initialization Timing Diagram

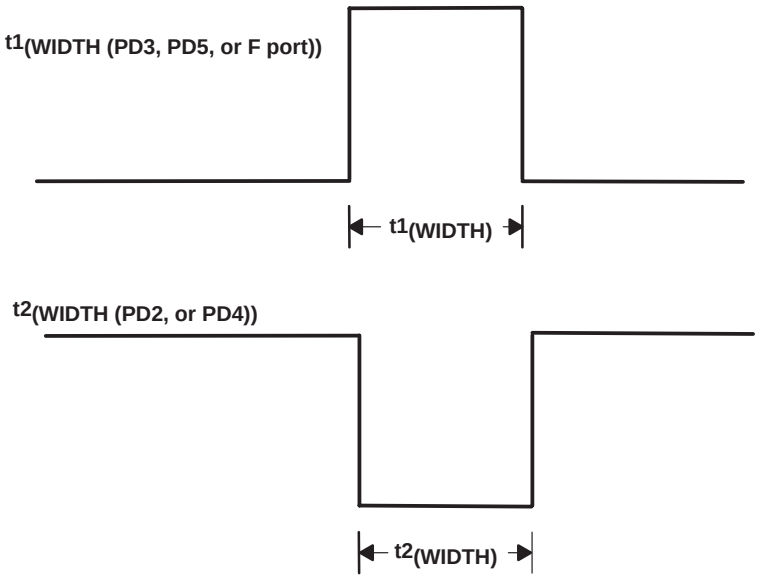


Figure 2. MSP50P614 External Interrupt Pin Pulse Width Requirements $t1_{WIDTH}$ and $t2_{WIDTH}$

dc electrical characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
RESET	Threshold changes	V_{DD} = 3 V	Positive going threshold		2.4		V
			Negative going threshold		1.8		
			Hysteresis		0.6		
		V_{DD} = 5.2 V	Positive going threshold		3.3		V
			Negative going threshold		2.9		
			Hysteresis		0.4		
I_{lkg}	Input leakage current	Excludes OSC_{IN}				1	µA
$I_{(STANDBY)}$	Standby current	RESET is low			0.05	10	µA
I_{DD}†	Operating current	V_{DD} = 4.5 V,	F_{CLOCK} = 12.32 MHz		15		mA
$I_{(SLEEP–deep)}$	Supply current	V_{DD} = 4.5 V,	DAC off, ARM set, OSC disabled		0.05	10	µA
$I_{(SLEEP–mid)}$		V_{DD} = 4.5 V,	DAC off, ARM set, OSC enabled		40	60	
$I_{(SLEEP–light)}$		V_{DD} = 4.5 V,	DAC off, ARM clear, OSC enabled		60	100	
V_{IO}	Input offset voltage	V_{DD} = 4.5 V,	Vref = 1 to 4.25 V		25	50	mV
$R_{(PULLUP)}$	F port pullup resistance	V_{DD} = 5 V		70	150		kΩ
$\Delta f_{(RTO–trim)}$	Trim deviation	R_{RTO} = 470 kΩ, V_{DD} = 4.5 V, T_A = 25°C, f_{RTO} = 8.192 MHz (PLL setting = 7 Ch)‡			±2	±3	%
$\Delta f_{(RTO–volt)}$	Voltage deviation	R_{RTO} = 470 kΩ, V_{DD} = 3.5 to 5.2 V, T_A = 25°C, f_{RTO} = 8.192 MHz (PLL setting = 7 Ch)‡				±1.5	%
$\Delta f_{(RTO–temp)}$	Temperature deviation	R_{RTO} = 470 kΩ, V_{DD} = 4.5 V, T_A = 0 to 70°C, f_{RTO} = 8.192 MHz (PLL setting = 7 Ch)‡		–0.1		0.1	%/°C
$\Delta f_{(RTO–res)}$	Resistance deviation	V_{DD} = 4.5 V,	T_A = 25°C, R_{OSC} = 470 kΩ @ ±1%, f_{RTO} = 8.192 MHz (PLL setting = 7 Ch)‡		±1		%

† Operating current assumes all inputs are tied to either V_{SS} or V_{DD} with no input currents due to programmed pullup resistors. The DAC output and other outputs are open circuited.

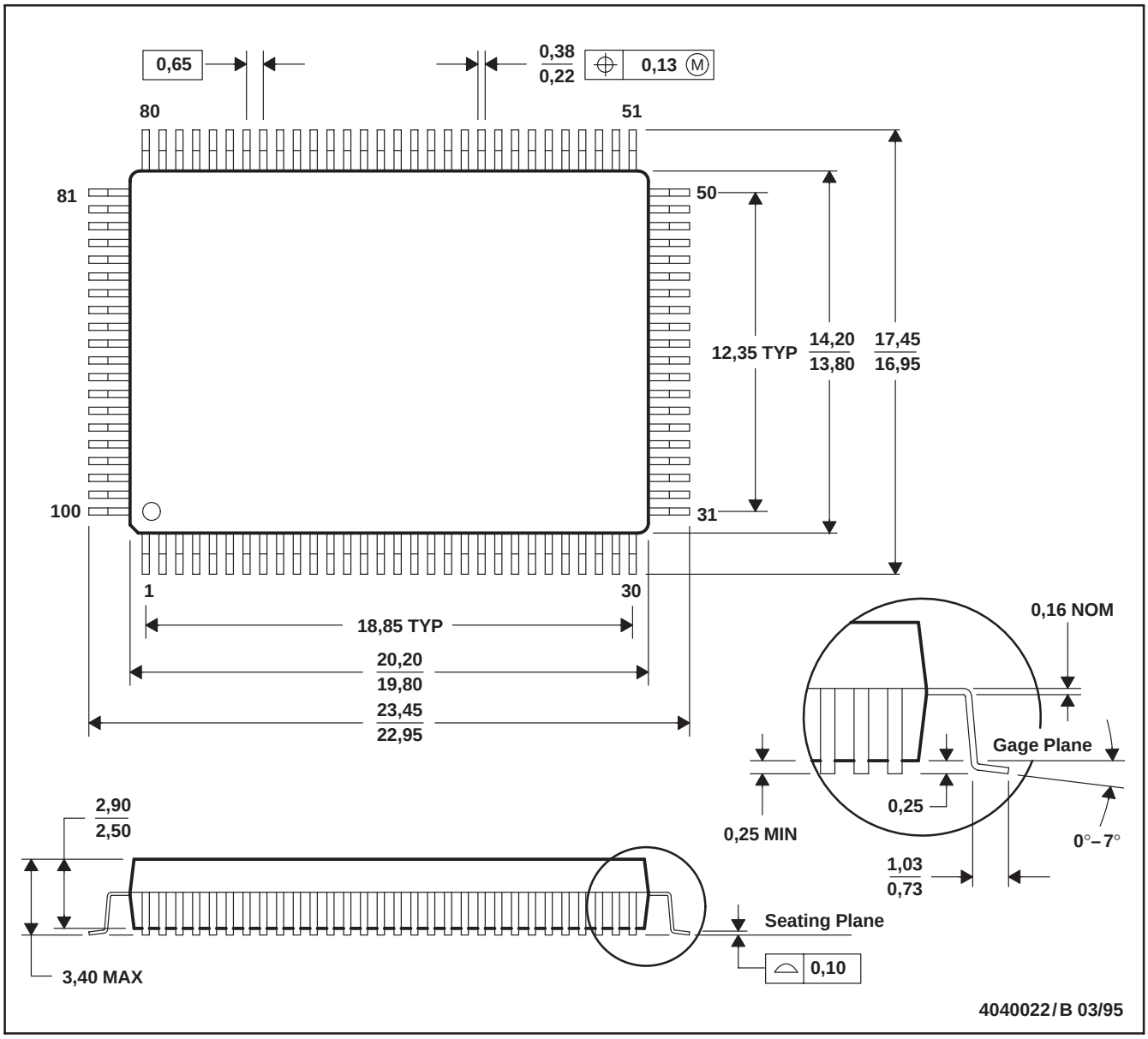
‡ The best trim value is selected at nominal temperature and voltage but the deviation due to the trim error is ignored.

external component absolute values

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$R_{(RTO)}$	RTO external resistance	T_A = 25°C,	1% tolerance		470	kΩ
$C_{(PLL)}$	PLL external capacitance	T_A = 25°C,	10% tolerance		3300	pF

MECHANICAL DATA

PJM (R-PQFP-G100) **PLASTIC QUAD FLATPACK**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-022

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